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電源管理



顯示驅動



二三極管



LDO穩壓器



觸摸芯片



MOS管



運算放大器



存儲芯片



MCU



串口通信

B360A

產品規格說明書

SURFACE MOUNT SCHOTTKYBARRIER RECTIFIER

Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Ultra fast switching for high efficiency
- ◆ Low reverse leakage
- ◆ Built-in strain relief,ideal for automated placement
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed
250 °C/10 seconds at terminals

Mechanical Data

Case : JEDEC DO-214AC/SMA Molded plastic body

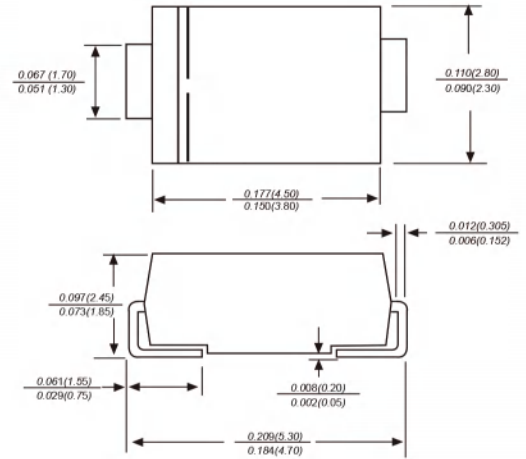
Terminals : Solder plated, solderable per MIL-STD-750,Method 2026

Polarity : Polarity symbol marking on body

Mounting Position : Any

Weight : 0.002 ounce, 0.07 grams

DO-214AC/SMA



Dimensions in inches and (millimeters)

Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

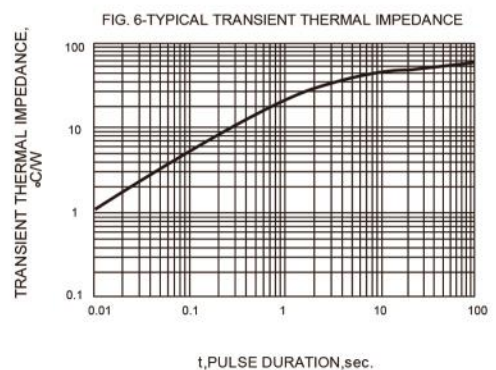
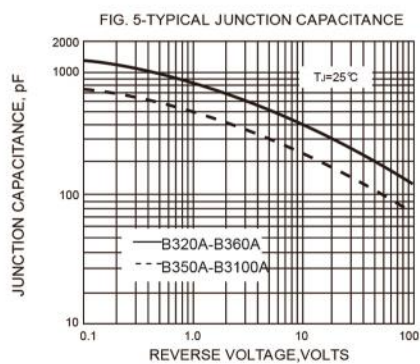
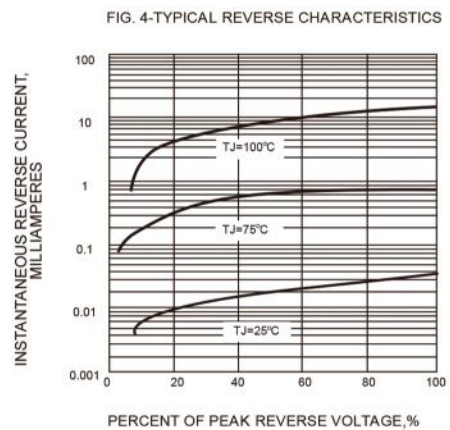
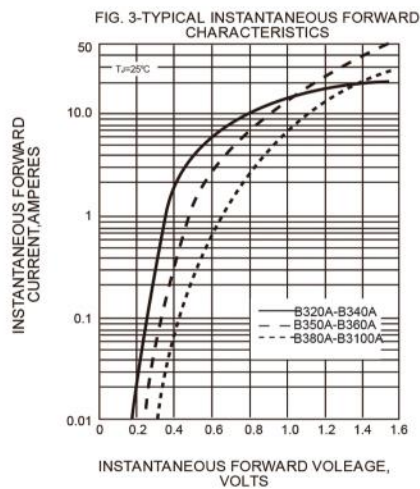
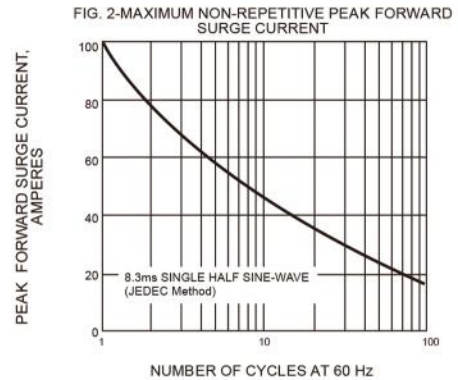
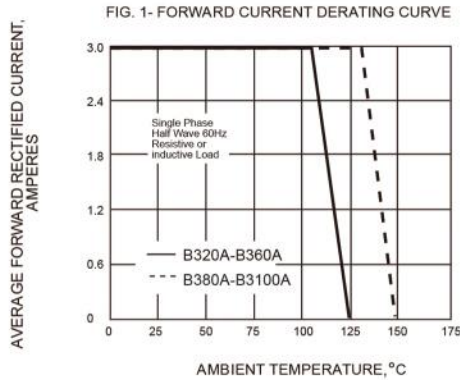
Single phase half-wave 60Hz,resistive or inductive load,for capacitive load current derate by 20%.

Parameter	SYMBOLS	MDD B320A	MDD B330A	MDD B340A	MDD B350A	A MDD B360A	MDD B380A	MDD B3100A	UNITS
Marking Code									
Maximum repetitive peak reverse voltage	V _{RRM}	20	30	40	50	60	80	100	V
Maximum RMS voltage	V _{RMS}	14	21	28	35	42	56	70	V
Maximum DC blocking voltage	V _{DC}	20	30	40	50	60	80	100	V
Maximum average forward rectified current at TL=55 °C	I _(AV)	3.0							A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	100							A
Maximum instantaneous forward voltage at 3.0A	V _F	0.55			0.70		0.85		V
Maximum DC reverse current TA=25 °C at rated DC blocking voltage TA=100 °C	I _R	0.5							mA
		20					10		
Typical junction capacitance (NOTE 1)	C _J	500			300				pF
Typical thermal resistance (NOTE 2)	R _{θJA}	55.0							°C/W
Operating junction and storage temperature range	T _J , T _{STG}	-50 to +150							°C

Note: 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

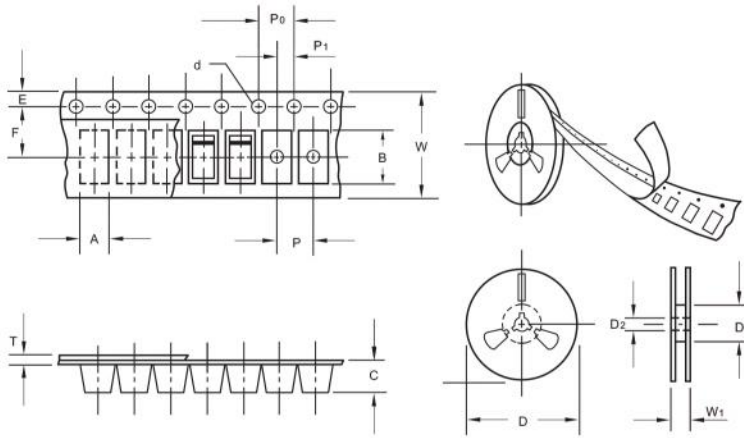
2. P.C.B. mounted with 0.2x0.2" (5.0x5.0mm) copper pad areas

Ratings And Characteristic Curves



The curve above is for reference only.

Packing information



unit:mm

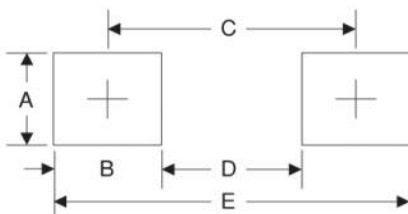
Item	Symbol	Tolerance	SMA
Carrier width	A	0.1	2.80
Carrier length	B	0.1	5.33
Carrier depth	C	0.1	2.36
Sprocket hole	d	0.05	1.50
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D ₁	min	50.00
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D ₁	min	62.00
Feed hole diameter	D ₂	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	5.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P ₀	0.1	4.00
Embossment center	P ₁	0.1	2.00
Overall tape thickness	T	0.1	0.28
Tape width	W	0.3	12.00
Reel width	W ₁	1.0	18.00

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMA	7"	2,000	4.0	4,000	183*155*183	178	382*356*392	80,000	16.0
SMA	11"	5,000	4.0	10,000	290*290*38	330	310*310*360	80,000	11.0
SMA	13"	7,500	4.0	15,000	335*335*38	330	350*330*360	120,000	14.5

Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	1.68	0.066
B	1.52	0.060
C	3.93	0.154
D	2.41	0.095
E	5.45	0.215